

SOT172D

CRDB4; blister pack; standard product orientation 12NC
ending 112

Rev. 1 — 18 October 2012

Packing information

1. Packing method

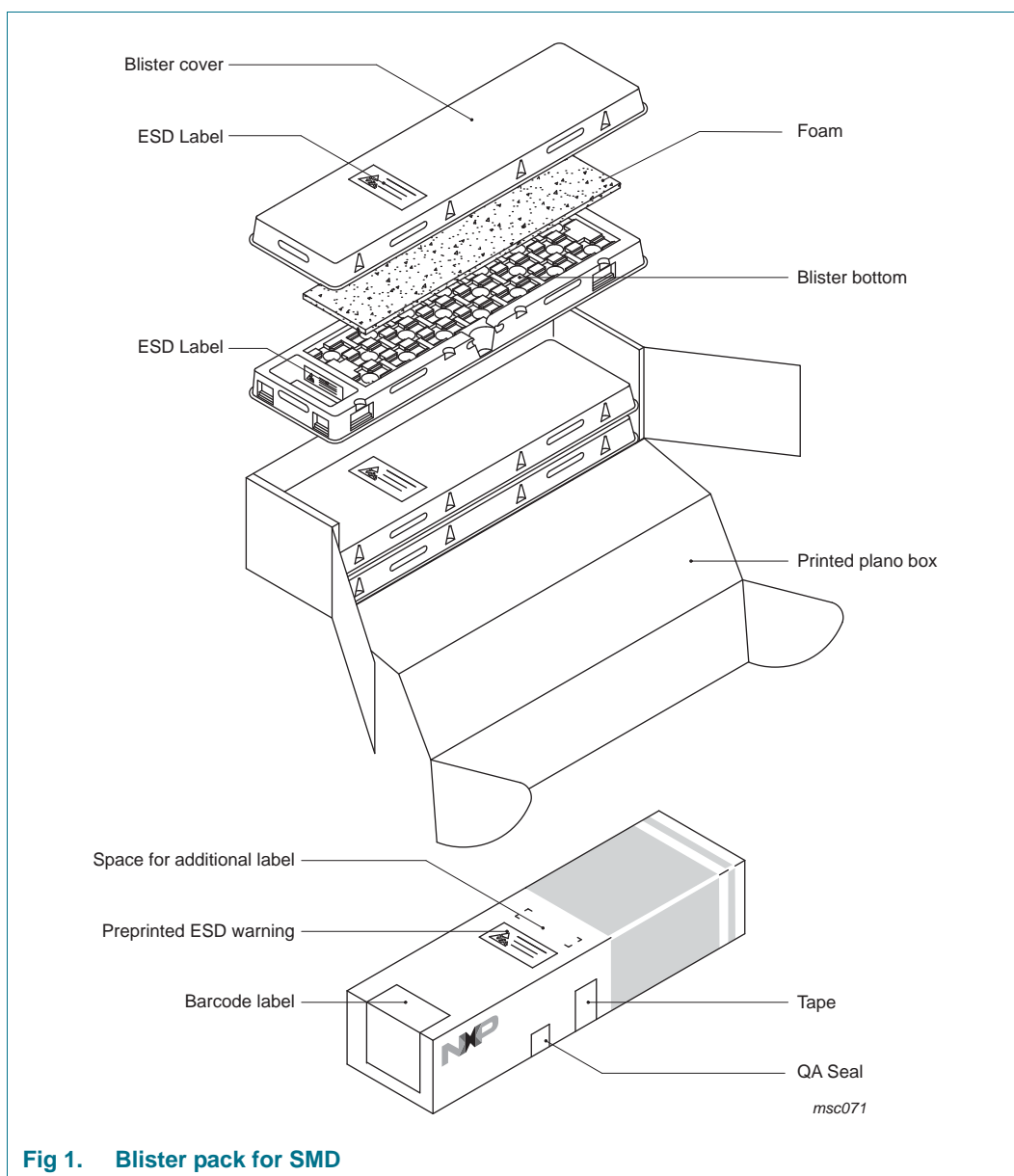


Fig 1. Blister pack for SMD

Table 1. Packing information

Package version	12NC ending	SPQ per carrier	PQ (pcs)	Carriers per box	Outer box dimensions l x w x h (mm)
SOT172D	112	20	40	2	315 x 118 x 78

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